

RCJ220N25

Nch 250V 22A Power MOSFET

V_{DSS}	250V
R _{DS(on)} (Max.)	140m Ω
I _D	22A
P_D	166W

Features

- 1) Low on-resistance.
- 2) Fast switching speed.
- 3) Drive circuits can be simple.
- 4) Parallel use is easy.
- 5) Pb-free lead plating; RoHS compliant
- 6) 100% Avalanche tested

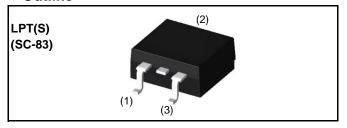
Application

Switching Power Supply

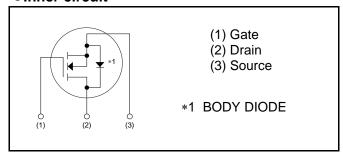
Automotive Motor Drive

Automotive Solenoid Drive

Outline



●Inner circuit



Packaging specifications

	Packaging	Taping
	Reel size (mm)	330
Type	Tape width (mm)	24
Type	Quantity (pcs)	1,000
	Taping code	TL
	Marking	RCJ220N25

• Absolute maximum ratings($T_a = 25$ °C)

Paramete	Symbol	Value	Unit	
Drain - Source voltage	V _{DSS}	250	V	
Continuous dusin suurent	$T_c = 25^{\circ}C$	I _D *1	±22	А
Continuous drain current	T _c = 100°C	I _D *1	±11.9	А
Pulsed drain current		I _{D,pulse} *2	±88	А
Gate - Source voltage		V_{GSS}	±30	V
Avalanche energy, single pulse		E _{AS} *3	36.8	mJ
Avalanche current		I _{AR} *3	11	А
Power discipation	T _c = 25°C	P _D	166	W
Power dissipation $T_a = 25^{\circ}C^{*4}$		P _D	1.56	W
Junction temperature		Tj	150	°C
Range of storage temperature		T _{stg}	-55 to +150	°C

●Thermal resistance

Parameter	Symbol	Values			Unit
- Farameter	Symbol	Min.	Тур.	Max.	Offic
Thermal resistance, junction - case	R_{thJC}	-	-	0.75	°C/W
Thermal resistance, junction - ambient *4	R_{thJA}	-	-	80	°C/W
Soldering temperature, wavesoldering for 10s	T _{sold}	-	-	265	°C

●Electrical characteristics(T_a = 25°C)

Parameter	Symbol Conditions		Values			Unit	
- Farameter	Symbol	Conditions	Min.	Тур.	Max.	UTIIL	
Drain - Source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0V$, $I_D = 1mA$	250	-	-	V	
Zero gate voltage drain current	I _{DSS}	$V_{DS} = 250V, V_{GS} = 0V$ $T_j = 25^{\circ}C$	ı	1	25	μΑ	
Gate - Source leakage current	I_{GSS}	$V_{GS} = \pm 30V, V_{DS} = 0V$	1	-	±100	nA	
Gate threshold voltage	V _{GS (th)}	$V_{DS} = 10V$, $I_D = 1mA$	3.0	-	5.0	V	
		$V_{GS} = 10V, I_D = 11A$	-	105	140		
Static drain - source on - state resistance	R _{DS(on)} *5	$V_{GS} = 10V, I_D = 11A$ $T_j = 125^{\circ}C$	-	230	320	mΩ	
Forward transfer admittance	g _{fs}	$V_{DS} = 10V, I_{D} = 11A$	6	12	-	S	

●Electrical characteristics(T_a = 25°C)

Parameter	Symbol	Conditions		Unit		
r ai ai ii e lei	Syllibol	Conditions	Min.	Тур.	Max.	Offic
Input capacitance	C_{iss}	$V_{GS} = 0V$	-	3200	-	
Output capacitance	C _{oss}	V _{DS} = 25V	-	170	-	pF
Reverse transfer capacitance	C_{rss}	f = 1MHz	-	100	-	
Turn - on delay time	t _{d(on)} *5	$V_{DD} \simeq 125V, V_{GS} = 10V$	-	45	-	
Rise time	t _r *5	I _D = 11A	-	100	-	nc
Turn - off delay time	t _{d(off)} *5	$R_L = 12\Omega$	-	75	-	ns
Fall time	t _f *5	$R_G = 10\Omega$	-	40	-	

• Gate Charge characteristics ($T_a = 25$ °C)

Parameter	Symbol	Conditions	Values			Unit
Parameter	Symbol	ol Conditions –		Тур.	Max.	Offic
Total gate charge	Q_g^{*5}	V _{DD} ≃ 125V	-	60	-	
Gate - Source charge	Q _{gs} *5	I _D = 22A	-	15	-	nC
Gate - Drain charge	Q _{gd} *5	V _{GS} = 10V	-	20	-	
Gate plateau voltage	V _(plateau)	$V_{DD} \simeq 125V, I_D = 22A$	-	7.4	-	V

●Body diode electrical characteristics (Source-Drain)(T_a = 25°C)

Parameter	Symbol	Conditions	Values			Unit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Offic
Continuous source current	I _S *1	T _c = 25°C	-	1	22	Α
Pulsed source current	I _{SM} *2	1 _c = 23 0	-	-	88	Α
Forward voltage	V _{SD} *5	$V_{GS} = 0V, I_{S} = 22A$	-	-	1.5	V
Reverse recovery time	t _{rr} *5	I _S = 11A	-	140	-	ns
Reverse recovery charge	Q _{rr} *5	di/dt = 100A/μs	-	660	-	nC

^{*1} Limited only by maximum temperature allowed.

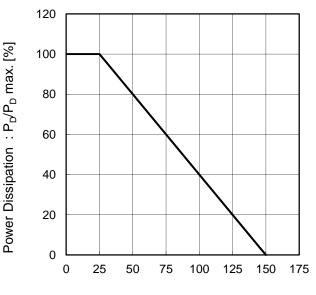
*5 Pulsed

^{*2} Pw \leq 10 μ s, Duty cycle \leq 1%

^{*3} L $^{\simeq}$ 500 μ H, V_{DD} = 50V, Rg = 25 Ω , starting T $_{j}$ = 25°C

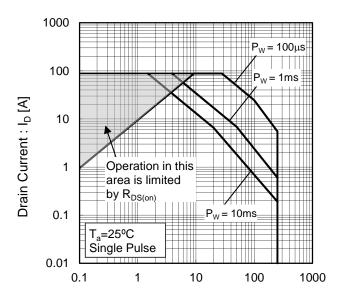
^{*4} Mounted on a epoxy PCB FR4 (25mm × 27mm × 0.8mm)

Fig.1 Power Dissipation Derating Curve



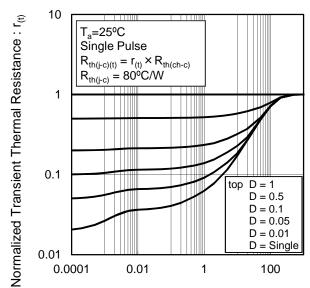
Junction Temperature : T_i [°C]

Fig.2 Maximum Safe Operating Area



Drain - Source Voltage : V_{DS} [V]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width



Pulse Width : $P_W[s]$

Fig.4 Avalanche Current vs Inductive Load

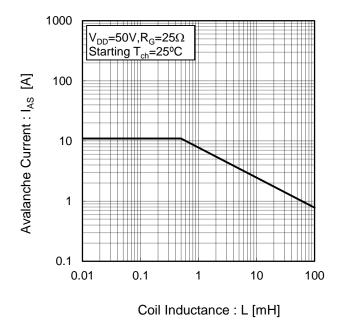
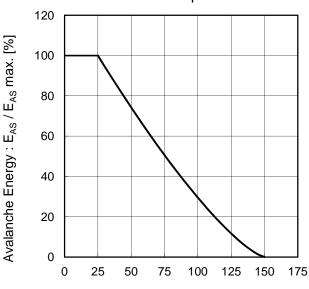
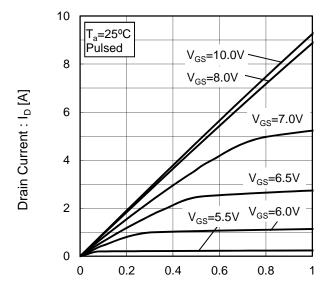


Fig.5 Avalanche Energy Derating Curve vs Junction Temperature



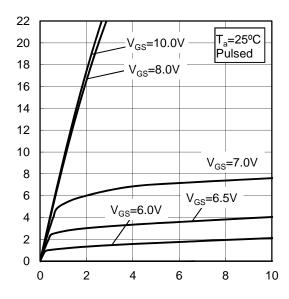
Junction Temperature : T_i [°C]

Fig.6 Typical Output Characteristics(I)



Drain - Source Voltage : V_{DS} [V]

Fig.7 Typical Output Characteristics(II)



Drain - Source Voltage : V_{DS} [V]

Drain Current : I_D [A]

Fig.8 Breakdown Voltage vs. Junction Temperature 340 Normarize Drain - Source Breakdown Voltage $V_{GS} = 0V$ $I_D = 1mA$ 320 300 $: V_{(BR)DSS}[V]$ 280 260 240 220 -50 0 50 100 150 Junction Temperature : T_i [°C]

100 $V_{DS} = 10V$ 10 Drain Current: I_D [A] $T_a = 125^{\circ}C$ $T_a = 75^{\circ}C$ 0.1 $T_a = 25^{\circ}C$ $T_a = -25^{\circ}C$ 0.01 0.001 0 2 3 4 5 8 9 10

Fig.9 Typical Transfer Characteristics

Fig.10 Gate Threshold Voltage vs. Junction Temperature

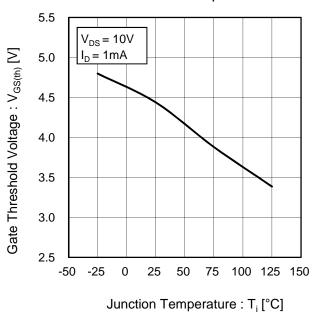
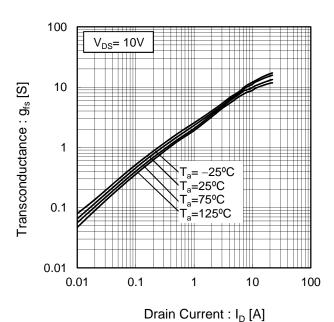


Fig.11 Transconductance vs. Drain Current

Gate - Source Voltage : V_{GS} [V]



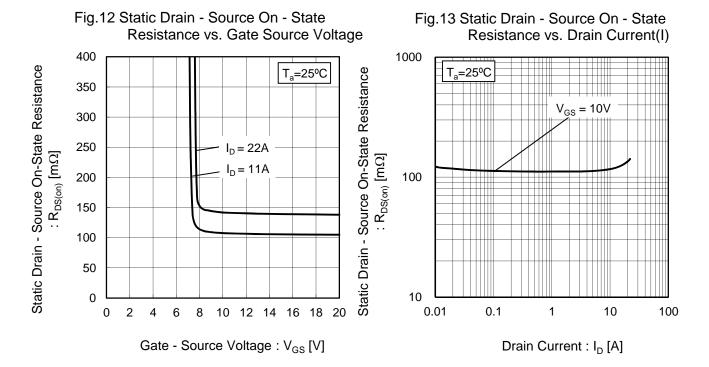
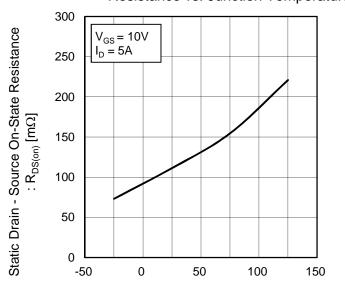


Fig.14 Static Drain - Source On - State Resistance vs. Junction Temperature



Junction Temperature : T_j [°C]

Resistance vs. Drain Current(II)

1000 $V_{GS} = 10V$ V_{G

Drain Current : I_D [A]

Fig.15 Static Drain - Source On - State

Fig.16 Drain Current Derating Curve

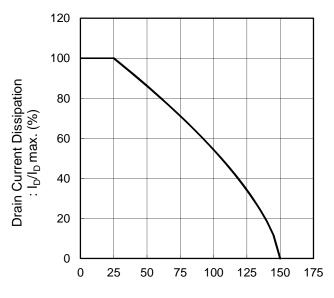


Fig.17 Typical Capacitance vs. Drain - Source Voltage

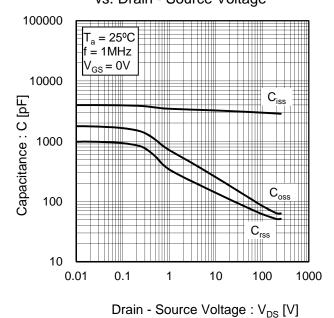
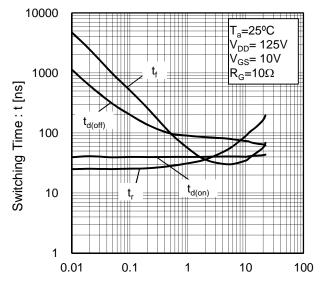
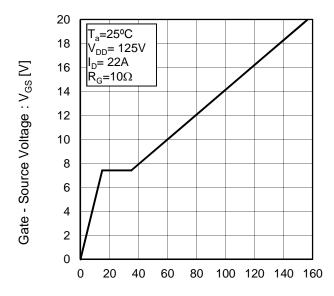


Fig.18 Switching Characteristics

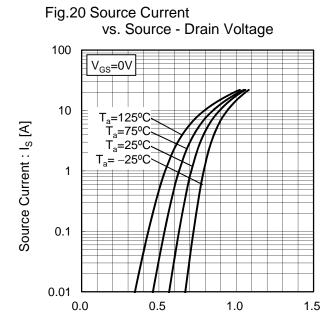


Drain Current : I_D [A]

Fig.19 Dynamic Input Characteristics



Total Gate Charge : Q_g [nC]



Vs. Source Current

10000

| Selection | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 10

Fig21 Reverse Recovery Time

●Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

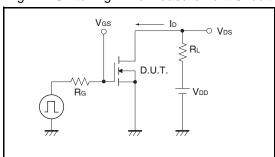


Fig.2-1 Gate Charge Measurement Circuit

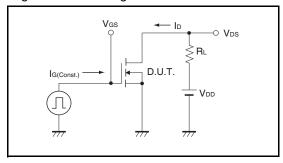


Fig.3-1 Avalanche Measurement Circuit

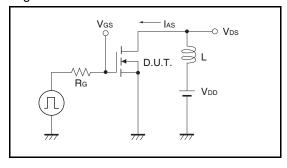


Fig.1-2 Switching Waveforms

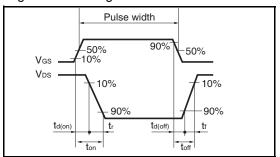


Fig.2-2 Gate Charge Waveform

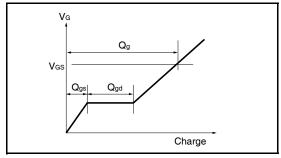
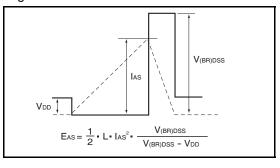
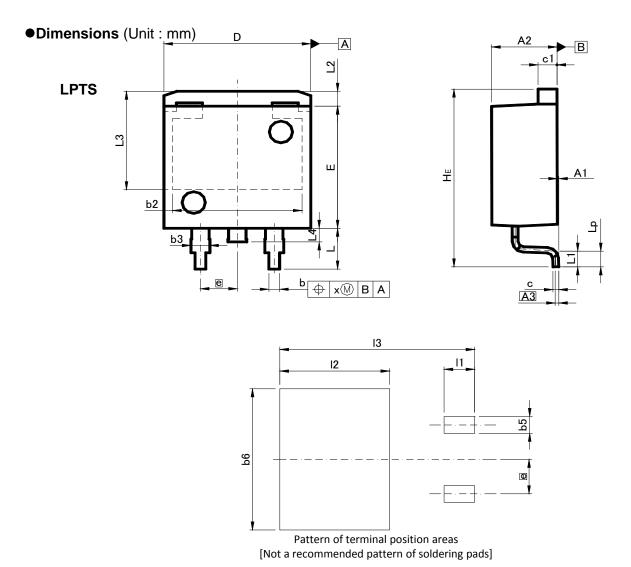


Fig.3-2 Avalanche Waveform





DIM	MILIMETERS		INC	HES
	MIN	MAX	MIN	MAX
A1	0.00	0.30	0.000	0.012
A2	4.30	4.70	0.169	0.185
A3	0.:	25	0.0	10
b	0.68	0.98	0.027	0.039
b2	8.	90	0.3	50
b3	1.14	1.44	0.045	0.057
С	0.30	0.60	0.012	0.024
c1	1.10	1.50	0.043	0.059
D	9.80	10.40	0.386	0.409
L	8.80	9.20	0.346	0.362
е	2.	54	0.1	00
HE	12.80	13.40	0.504	0.528
L	2.70	3.30	0.106	0.130
L1	0.90	1.50	0.035	0.059
L2	1.	10	0.0	43
L3	7.	25	0.2	85
L4	1.	00	0.0	39
Lp	0.90	1.50	0.035	0.059
Х	_	0.25	_	0.010

DIM	MILIMETERS		INC	HES
DIM	MIN	MAX	MIN	MAX
bb	-	1.23	-	0.049
b6	_	10.40	-	0.409
- 11	-	2.10	-	0.083
12	-	7.55	-	0.297
13	_	13.40	_	0.528

Dimension in mm / inches

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CLASSIV	CLASSⅢ	CLASSⅢ	CLASSⅢ

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- 8. Confirm that operation temperature is within the specified range described in the product specification.
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 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
 may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
 exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
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